



PRODUCT DATASHEET



Release Date: 13 April 2016 Version: A1.0



PLCC4 3528 1.8t



FEATURES:

- Package: PLCC4 Top View SMT White Package
- Forward Current: 50mA
- Forward Voltage (typ.): 3.6V
- Luminous Intensity (typ.): 1550mcd@50mA
- Colour: Green
- Wavelength: 520nm
- Viewing angle: 120°
- Materials:
 - Die: InGaN
 - Resin: Silicone (Water Clear)
 - L/F Finish: Ag Plated
- Operating Temperature: -40~+80°C
- Storage Temperature: -40~+85°C
- Grouping parameters:
 - Forward voltage
 - Luminous intensity
 - Dominant Wavelength
- Soldering methods: Reflow soldering
- **Preconditioning:** acc. to JEDEC Level 3
- Packing: 8mm tape with 2000pcs/reel, ø180mm (7")

N0G19S74

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APPLICATIONS:

- LED Display
- Indicator

- Traffic Display
- Decoration Lighting



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	50	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	200	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

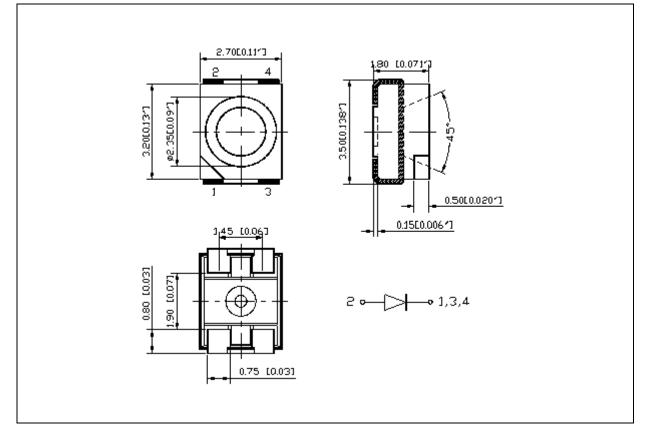
Parameter	Symbol	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V _F	2.8	3.6	4.0	V	I _F =50mA
Luminous Intensity	Iv	800	1550	2500	mcd	I _F =50mA
Dominant Wavelength	λ_{D}	515	520	525	nm	I _F =50mA
Peak Wavelength	λ_{P}		515		nm	I _F =50mA
Spectral Half Bandwidth	Δλ		35		nm	I _F =50mA
Viewing Angle	20 _{1/2}		120		deg	I _F =50mA

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V



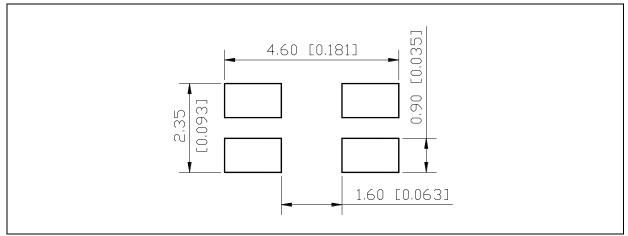


Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm.



BINNING GROUPS:

Code	Min.	Max.	Unit
F	2.8	3.1	
G	3.1	3.4	V
Н	3.4	3.7	V
I	3.7	4.0	

Forward Voltage Classifications ($I_F = 50mA$):

Luminous Intensity Classifications (I_F = 50mA):

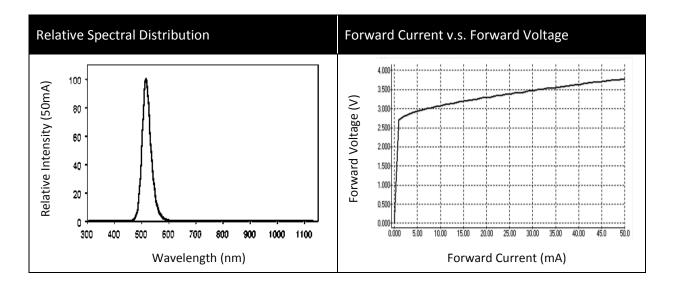
Code	Min.	Max.	Unit
S	800	1000	
Т	1000	1250	
U	1250	1600	mcd
V	1600	2000	
W	2000	2500	

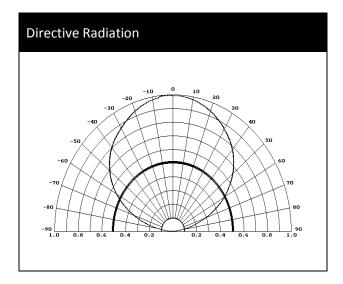
Wavelength Classifications ($I_F = 50 \text{mA}$):

Code	Min.	Max.	Unit
S	515	517.5	
Т	517.5	520	
U	520	522.5	nm
V	522.5	525	



ELECTRO-OPTICAL CHARACTERISTICS:

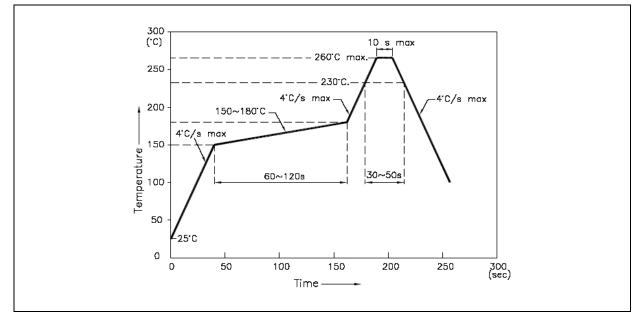






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



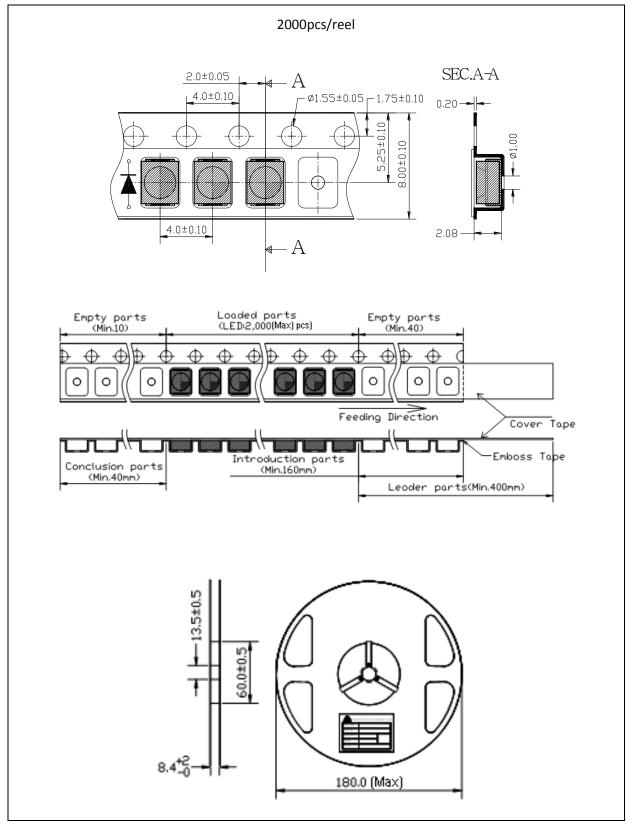
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. The recommend soldering temperature is 245°C. The maximum soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

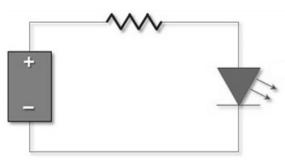
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 70±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	13/04/2016	Datasheet set-up.